

Electronic Patent Application Fee Transmittal

| Application Number: | 10557694 | | | |
|---|--|----------|--------|----------------------|
| Filing Date: | 22-Nov-2005 | | | |
| Title of Invention: | Resin for photoresist composition, photoresist composition and method for forming resist pattern | | | |
| First Named Inventor/Applicant Name: | Hideo Hada | | | |
| Filer: | Neil S. Bartfeld/L. Racquel Raymond | | | |
| Attorney Docket Number: | SHIGA7.033APC | | | |
| Filed as Large Entity | | | | |
| U.S. National Stage under 35 USC 371 Filing Fees | | | | |
| Description | Fee Code | Quantity | Amount | Sub-Total in USD(\$) |
| Basic Filing: | | | | |
| Pages: | | | | |
| Claims: | | | | |
| Miscellaneous-Filing: | | | | |
| Petition: | | | | |
| Patent-Appeals-and-Interference: | | | | |
| Post-Allowance-and-Post-Issuance: | | | | |
| Extension-of-Time: | | | | |
| Extension - 1 month with \$0 paid | 1251 | 1 | 120 | 120 |

| Description | Fee Code | Quantity | Amount | Sub-Total in USD(\$) |
|-------------------|----------|----------|--------|----------------------|
| Miscellaneous: | | | | |
| Total in USD (\$) | | | | 120 |